



GooLED-SEO-6850 Pin Fin Heat Sink Φ68mm for Seoul

Features VS Benefits

- * The GooLED-SEO-6850 Seoul Pin Fin LED Heat Sinks are specifically designed for luminaires using the Seoul LED engines.
- * Mechanical compatibility with direct mounting of the LED engines to the LED cooler and thermal performance matching the lumen packages.
- * For spotlight and downlight designs from 900 to 2,600 lumen.
- * Thermal resistance range Rth 3.23°C/W.
- * Modular design with mounting holes foreseen for direct mounting of Seoul COB series and AC Modules
- * Diameter 68.0mm standard height 50.0mm, Other heights on request.
- * Forged from highly conductive aluminum.

Zhaga LED engine and radiator assembly is a unified future international standardization

- * Below you find an overview of Seoul COB's and LED modules which standard fit on the Pin Fin LED Heat Sinks.
- * In this way mechanical after work and related costs can be avoided, and lighting designers can standardize their designs on a limited number of LED Pin Fin LED Heat Sink.



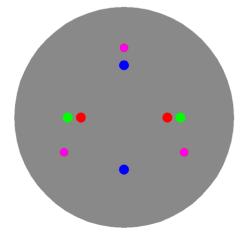












Seoul LED Modules directly Mounting Options Seoul COB Series, Size 28×28mm.

SDW04F1C; SDW05F1C; SDW06F1C: SDW94F1C;

Direct mounting with machine screws M3x6.5mm

Seoul COB Series, Size 19×19mm.

SDW02F1C; SDW82F1C; SDW83F1C;

BJB holder: 47.319.2021.50; AAG.STUCCHI: 8101-G2 Without the holders for the red indicator marks.

Direct mounting with machine screws M3x6.5mm

AC LED Modules, Size Φ46mm.

SMJE-2D08W4PD; SMJD-3D08W4PD; SMJE-2D12W4PE; SMJD-3D12W4PE;

Direct mounting with 3 screws M2x6.5mm.







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Mounting Options and Drawings & Dimensions

Example:GooLED-SEO-6850-B-1,2

Example:GooLED-SEO-68 1 - 2 -



2 Anodising Color

B-Black

C-Clear

Z-Custom

Mounting Options - see graphics for details Combinations available

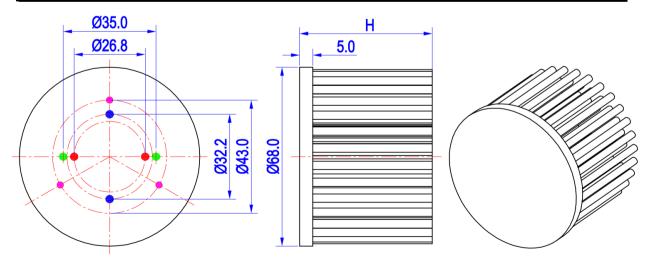
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means option 1 and 2 combined

Notes:

- Mentioned models are an extraction of full product range.
- For specific mechanical adaptations please contact MingfaTech.
- MingfaTech reserves the right to change products or specifications without prior notice.

MOUNTING OPTION	Module type	Holder NO.	LEDiL products		TUDEAD	THREAD	THREAD HOLE
			Olivia series	Ronda series	THREAD	DEPTH	DISTANCE
1	COB Size 19×19mm	/	FN14637-S; FN14828-M;	FN15xxx-xx;	М3	6.5mm	26.8mm/ 2-@180°
2	COB Size 28x28mm	1	/	/	M3	6.5mm	32.2mm/ 2-@180°
3		BJB Holder 47.319.2030.50		/	• мз	6.5mm	35.0mm/ 2-@180° (Zhaga book 3)
		AAG.STUCCHI 8102-G2					
	COB Size 19x19mm	BJB Holder 47.319.2021.50	FN14637-S; FN14828-M;	FN15xxx-xx;			
		AAG.STUCCHI 8101-G2					
4	AC Module	/	1	/	M2	6.5mm	43.0mm/ 3-@120°



Tel:+86-769-39023131
Fax:+86-(020)28819702 ext:22122
Email:sales@mingfatech.com
Http://www.heatsinkled.com
Http://www.mingfatech.com





The product deta table

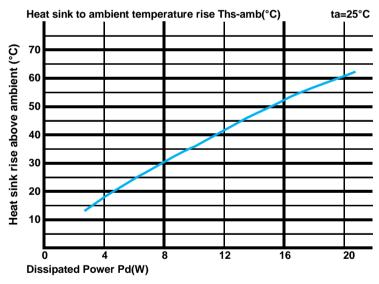


Model No.	GooLED-SEO-6850		
Heatsink Size	Ф68хH50mm		
Heatsink Material	AL1070		
Finish	Black Anodized		
Weight (g)	153.0		
Dissipated power (Ths-amb,50℃)	15.5 (W)		
Cooling surface area (mm²)	59562		
Thermal Resistance (Rhs-amb)	3.23 (°C/W)		

The thermal data table

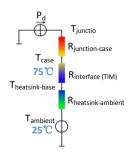
- * Please be aware the dissipated power Pd is not the same as the electrical power Pe of a LED module.
- *To calculate the dissipated power please use the following formula: $Pd = Pe \times (1-\eta L)$.
- Pd Dissipated power ; Pe Electrical power ; $\eta L =$ Light effciency of the LED module;

Pd = Pe x (1-ηL)		Heat sink to ambient thermal resistance Rhs-amb (°C/W)	Heat sink to ambient temperature rise Ths-amb (°C)		
		GooLED-SEO-6850			
Dissipated Power Pd(W)	4.0	4.25	17.0		
	8.0	3.75	30.0		
	12.0	3.42	41.0		
	16.0	3.25	52.0		
	20.0	3.00	60.0		



- *The aluminum substrate side of the package outer shell is thermally connected to the heat sink via TIM (Thermal interface material).
- $\label{thm:mingFa} \mbox{MingFa recommends the use of a high thermal conductive interface between the LED module and the LED cooler.}$

 $Either thermal\ grease, A\ thermal\ pad\ or\ a\ phase\ change\ thermal\ pad\ thickness\ 0.\ I-0.\ I\ 5mm\ is\ recommended.$



- *Thermal resistance is a heat property and a measurement of a temperature difference by which an object or material resists a heat flow. Geometric shapes are different, the thermal resistance is different. Formula: $\theta = (Ths Ta)/Pd$
- $\theta\,$ Thermal Resistance [°C/W] ; Ths - Heatsink temperature ; Ta - Ambient temperature ;
- *The thermal resistance between the junction section of the light-emitting diode and the aluminum substrate side of the package outer shell is $R_{junction-case}$, the thermal resistance of the TIM outside the package is $R_{interface (TIM)}$ [°C/M], the thermal resistance with the heat sink is $R_{heatsink-ambient}$ [°C/M], and the ambient temperature is $T_{ambient}$ [°C].
- *Thermal resistances outside the package $R_{interface \, (TIM)}$ and $R_{heatsink-ambient}$ can be integrated into the thermal resistance $R_{case-ambient}$ at this point. Thus, the following formula is also used:

 $T_{junction} = (R_{junction-case} + R_{case-ambient}) \cdot Pd + T_{ambient}$